TOSHIBA SG1400EX25

TENTATIVE

TOSHIBA GATE TURN-OFF THYRISTOR

SG1400EX25

: $V_{DRM} = 2500V$ Repetitive Peak Off-State Voltage

(Note 1)

Repetitive Peak Reverse Voltage $: V_{RRM} = 500V$

R.M.S On-State Current $: I_{T(RMS)} = 700A$

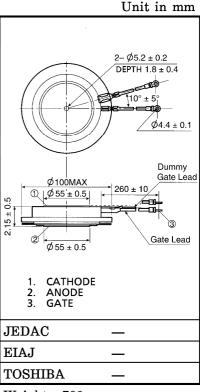
Peak Turn-Off Current $: I_{TGQM} = 1400A$

Critical Rate of Rise of On-State Current : $di/dt = 250A/\mu s$

Critical Rate of Rise of Off-State Voltage : $dv/dt=500V/\mu s$

MAXIMUM RATINGS

CHARACTERISTICS	SYMBOL	RATING	UNIT	
Repetitive Peak Off-State Voltage (Note 1)	$v_{ m DRM}$	2500	V	
Repetitive Peak Reverse Voltage	v_{RRM}	500	V	
Peak Turn-Off Current (Note 2)	ITGQM	1400	Α	
R.M.S On-State Current (Note 3)	I _T (RMS)	700	Α	
Peak One Cycle Surge On-State Current (Non Repetitive, Half Sine	irrent (Non Repetitive, Half Sine I _{TSM}			
Waveform)		-		
Critical Rate of Rise of On-State Current (Note 4)	di/dt	250	A/μs	
Peak Forward Gate Current	I_{FGM}	20	A	
Average Forward Gate Power Dissipation	P _{FG (AV)}	4	w	
R.M.S Gate Current (Note 5)	I _G (RMS)	42	Α	
Peak Reverse Gate Voltage (At Static)	V_{RGM}	15	v	
Operating Junction Temperature Range	$T_{\rm j}$	-40~115	°C	
Storage Temperature Range	$T_{ m stg}$	-40~115	°C	
Mounting Force	_	19.6 ± 2.0	kN	



Weight: 700g

- (Note 1) $R_{GK} \leq 20\Omega$
- $V_D = 1250V, \ V_{DM} \le 1700V, \ C_S \ge 2\mu F, \ di_{GQ} / dt \ge 30A / \mu s, \ V_{DSP} \le 600V, \ L_S \le 0.2\mu H$ (Note 2) (TOSHIBA method)
- (Note 3) 50Hz Half Sine Waveform
- $V_{D} \!\! \leq \! 1250 \text{V}, \; I_{TM} \!\! \leq \! 1400 \text{A}, \; I_{G} \!\! \geq \! 20 \text{A} \; (t_{r} \!\! \leq \! 1 \mu \text{s}), \; f \!\! \leq \! 50 \text{Hz}, \; C_{S} \!\! \leq \! 2 \mu \text{F}, \; R_{S} \!\! \geq \! 10 \Omega,$ (Note 4) $25^{\circ}\text{C} \leq \text{T}_{i} \leq 115^{\circ}\text{C}$
- (Note 5) Ambient Temperature of gate and cathode leading wire=90°C

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ELECTRICAL CHARACTERISTICS

ELLCTRICAL CHARACTERISTICS	1	1					
CHARACTERISTICS	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Repetitive Peak Off-State Current	$I_{ m DRM}$	$V_{DRM} = 2500V, V_{GK} = -2V$ $T_{j} = 115$ °C		_	_	50	mA
Repetitive Peak Reverse Current	I _{RRM}	V_{RRM} =500V T_j =115°C		_	_	50	mA
Repetitive Peak Reverse Gate Current	IRGM	$V_{RGM} = 15V$ $T_j = 115$ °C		_	_	100	mA
Peak On-State Voltage	V_{TM}	$I_{TM} = 1400A, T_j = 25^{\circ}C$		—		2.62	V
Gate Trigger Voltage	v_{GT}		$T_j = -40$ °C	_	_	3.0	V
		$V_{D}=24V$	$T_j = 25$ °C	_		1.5	V
Gate Trigger Current	I_{GT}	$R_{\rm L} = 0.2\Omega$	$T_j = -40$ °C	_		 	Α
			$T_j = 25$ °C	_		1.5	A
Turn-On Delay Time	^t d	$V_D = 1250V, I_{TM} = 1400A$ di / dt = 250A / μs		_	_	6.0	μs
Turn-On Time	\mathbf{t}_{gt}	I_{GM} =20A (t_r =1 μ s), T_j =25°C, non-snubber		_	_	12	μs
Critical Rate of Rise of Off- State Voltage	dv/dt	$V_{ m DRM}$ = 1700V $T_{ m j}$ = 115°C, $V_{ m GK}$ = -4V Exponential Rise		500	_	_	V / μs
Storage Time	t_S	I _{TGQ} =1400A		_		20	μ s
Gate Turn-Off Time	t_{gq}	$V_{DM} = 1700V, T_j = 115^{\circ}C$		_	_	25	μs
Tail Time	t _{tail}	$V_D = 1250V, C_S = 2\mu F$		_	160	_	μs
Turn-Off Gate Current	I_{GQ}	di _{GQ} /dt=30A/μs Off squeeze current≧300mA		_	350	_	A
Thermal Resistance	R _{th (j-f)}	Junction to fin		_	_	0.03	°C/W